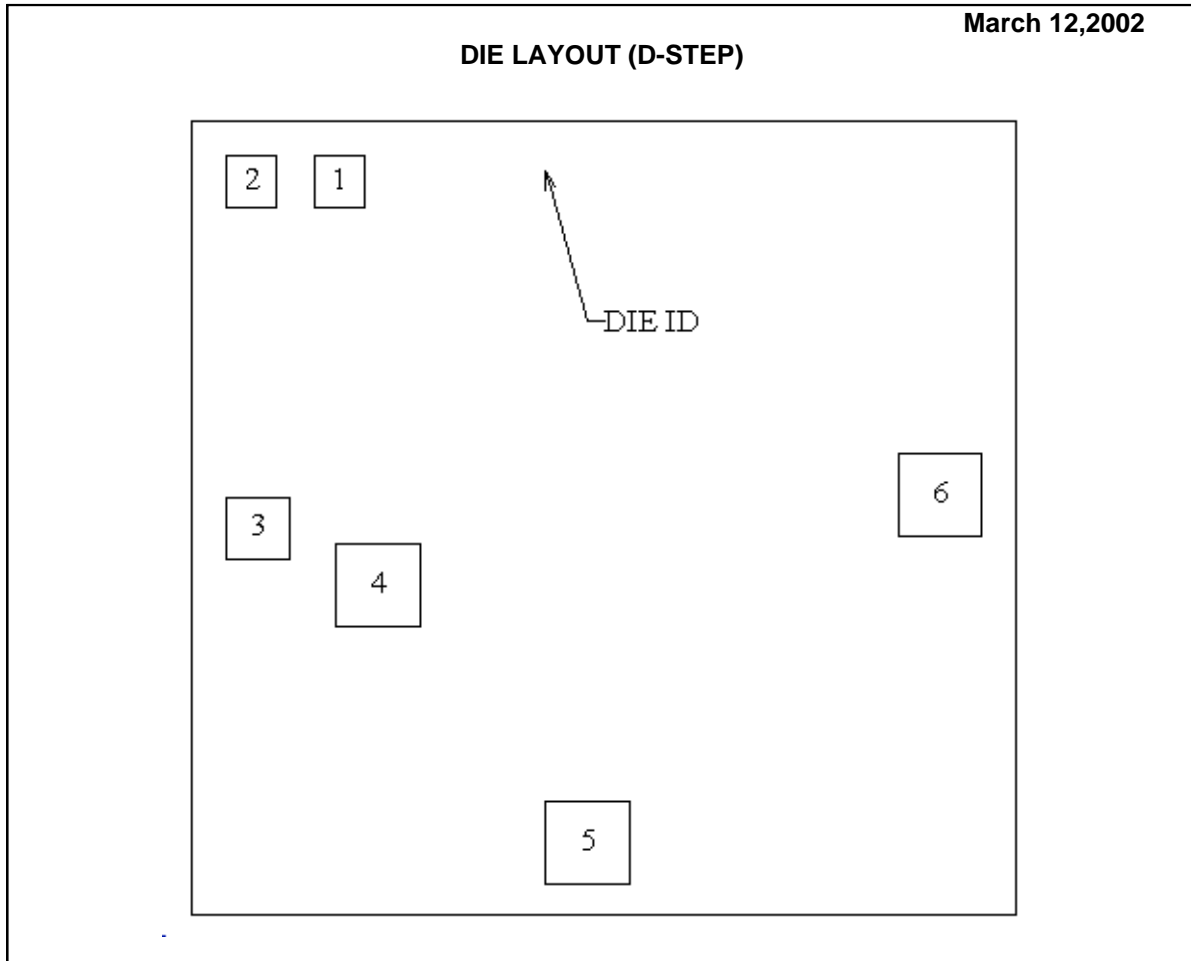


**LM120HG-5 MD8 MW8
SERIES 3-TERMINAL NEGATIVE REGULATORS**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM056D	Bond Pad Opening Size (min)	193µm x 193µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	100mm	Back Side Metal	Gold
Die Size (Drawn)	1829µm x 1905µm 72mils x 75mils	Back Side Connection	INPUT
Thickness	254µm Nominal		
Min Pitch	765µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
NC	1	-610	775	117	x	117
NC	2	-813	775	117	x	117
NC	3	-798	-25	147	x	142
OUTPUT	4	-521	-155	193	x	193
INPUT	5	-38	-749	193	x	193
GND	6	775	53	193	x	193

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